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(12) **United States Design Patent**
Laffon de Mazieres et al.

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(54) **ELECTRONIC DEVICE CABLE**

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(**) Term: **14 Years**

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(51) **LOC (10) Cl.** **14-02**

(52) **U.S. Cl.**
USPC **D14/433; D13/154**

(58) **Field of Classification Search**
USPC D13/147, 154, 153, 139, 156, 133, 108,
D13/137.2, 139.7, 173; D14/317, 357, 432,
D14/433, 434, 435.1, 507, 138 C, 356, 142,
D14/144; 439/887, 352, 607, 502; 361/679
CPC H01R 31/06
See application file for complete search history.

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(Continued)

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Assistant Examiner — Kendra L Hamilton

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(57) **CLAIM**

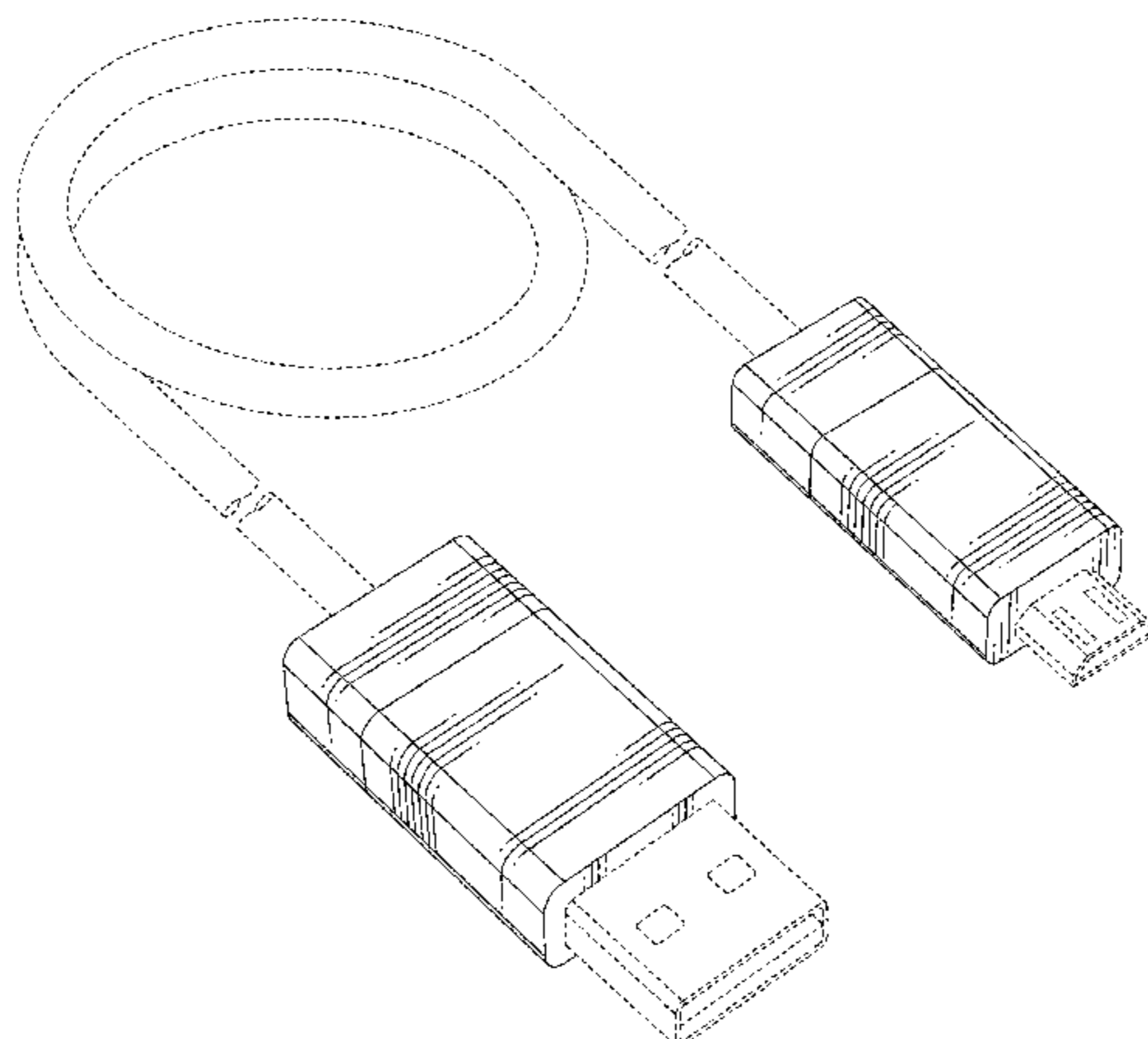
The ornamental design for an electronic device cable, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of an electronic device cable; FIG. 2 is another perspective view of the electronic device cable of FIG. 1; FIG. 3 is a top plan view of the electronic device cable of FIG. 1; FIG. 4 is a bottom plan view of the electronic device cable of FIG. 1; FIG. 5 is a back elevation view of the electronic device cable of FIG. 1; FIG. 6 is a partial cross-sectional view of the electronic device cable of FIG. 1, taken along line 6-6 in FIG. 5; FIG. 7 is a partial cross-sectional view of the electronic device cable of FIG. 1, taken along line 7-7 in FIG. 5; FIG. 8 is a front elevation view of the electronic device cable of FIG. 1; FIG. 9 is a left-side elevation view of the electronic device cable of FIG. 1; and, FIG. 10 is a right-side elevation view of the electronic device cable of FIG. 1.

The broken lines are directed to unclaimed portions and form no part of the claimed design.

1 Claim, 6 Drawing Sheets



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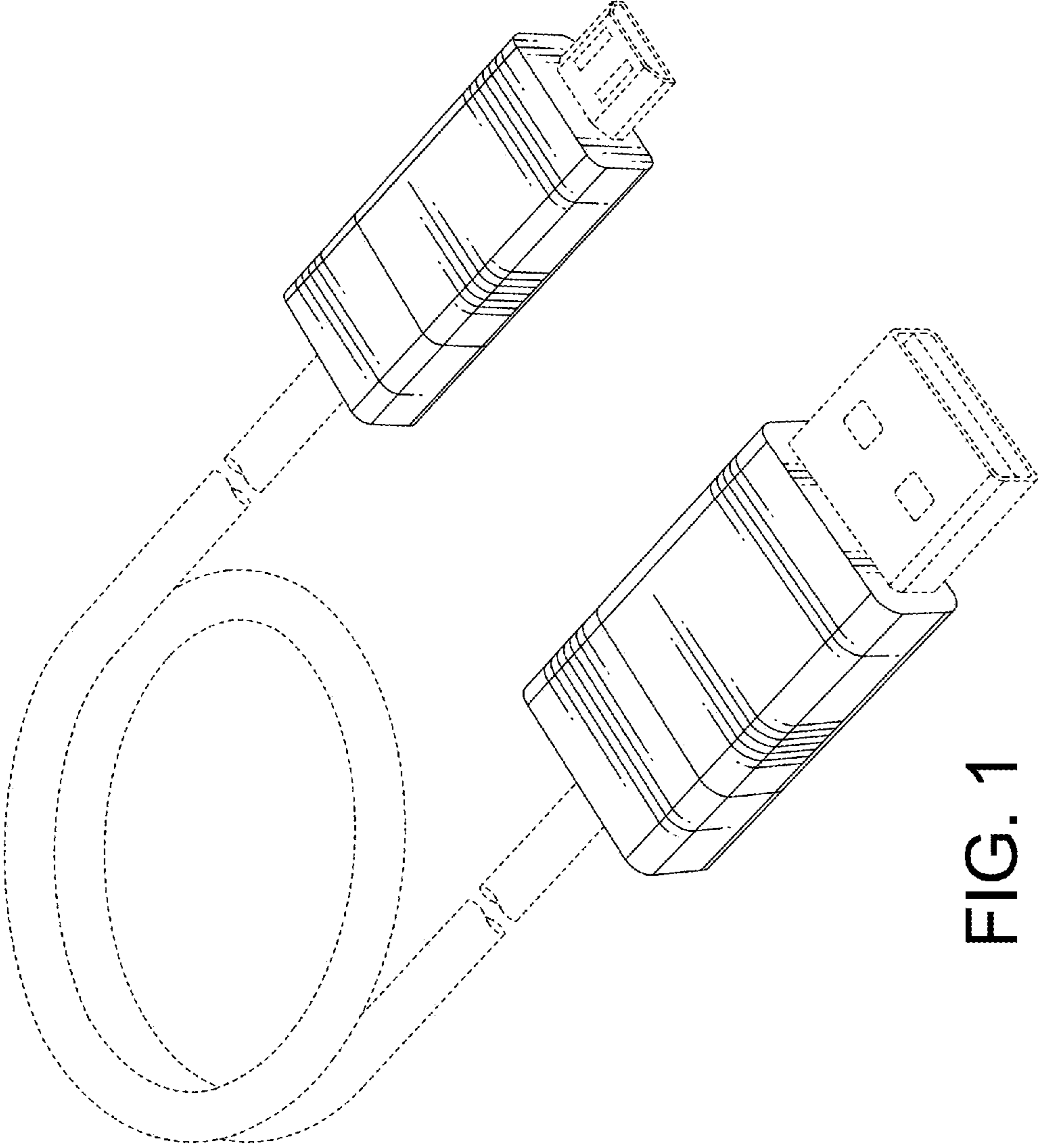


FIG. 1

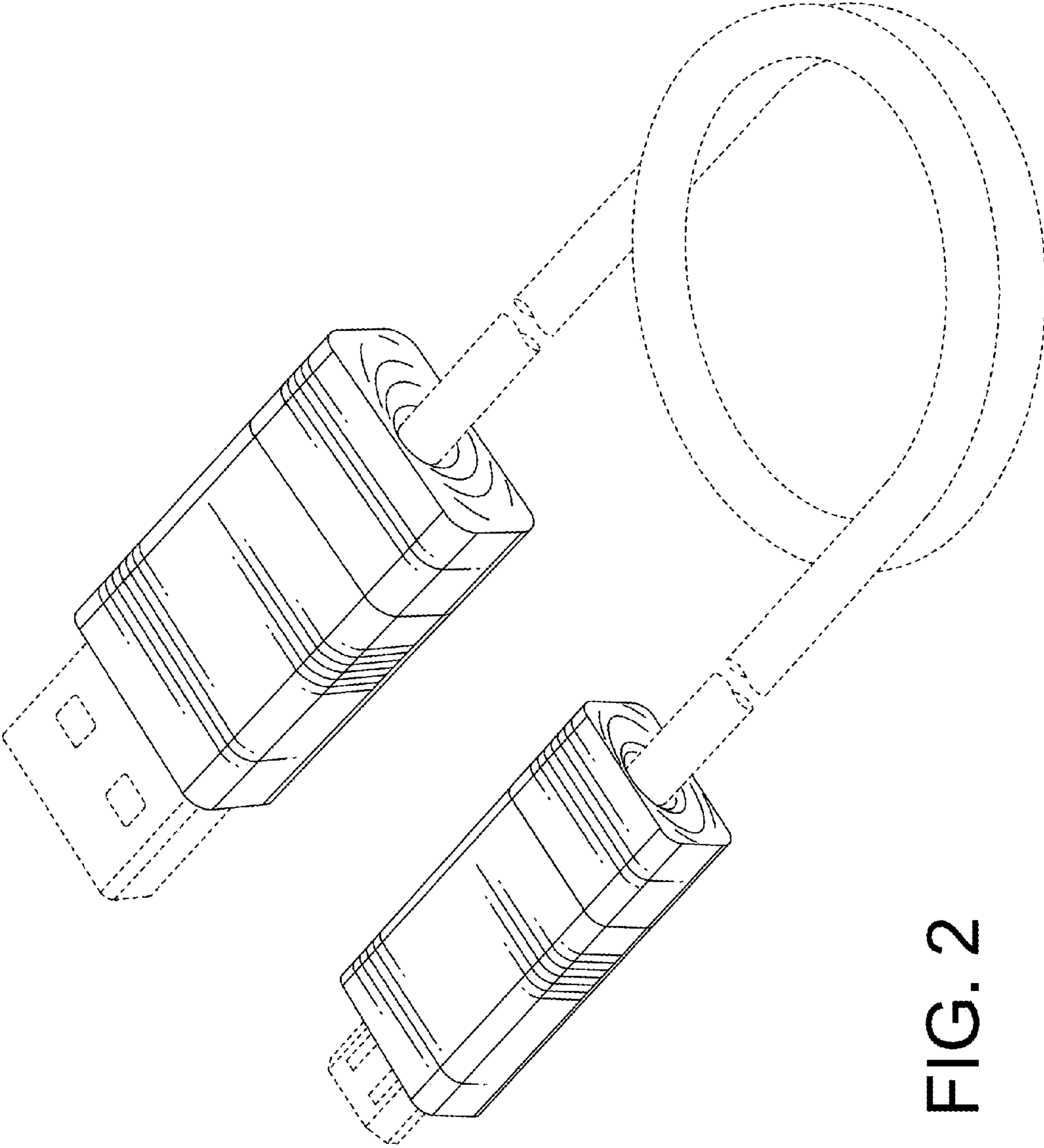


FIG. 2

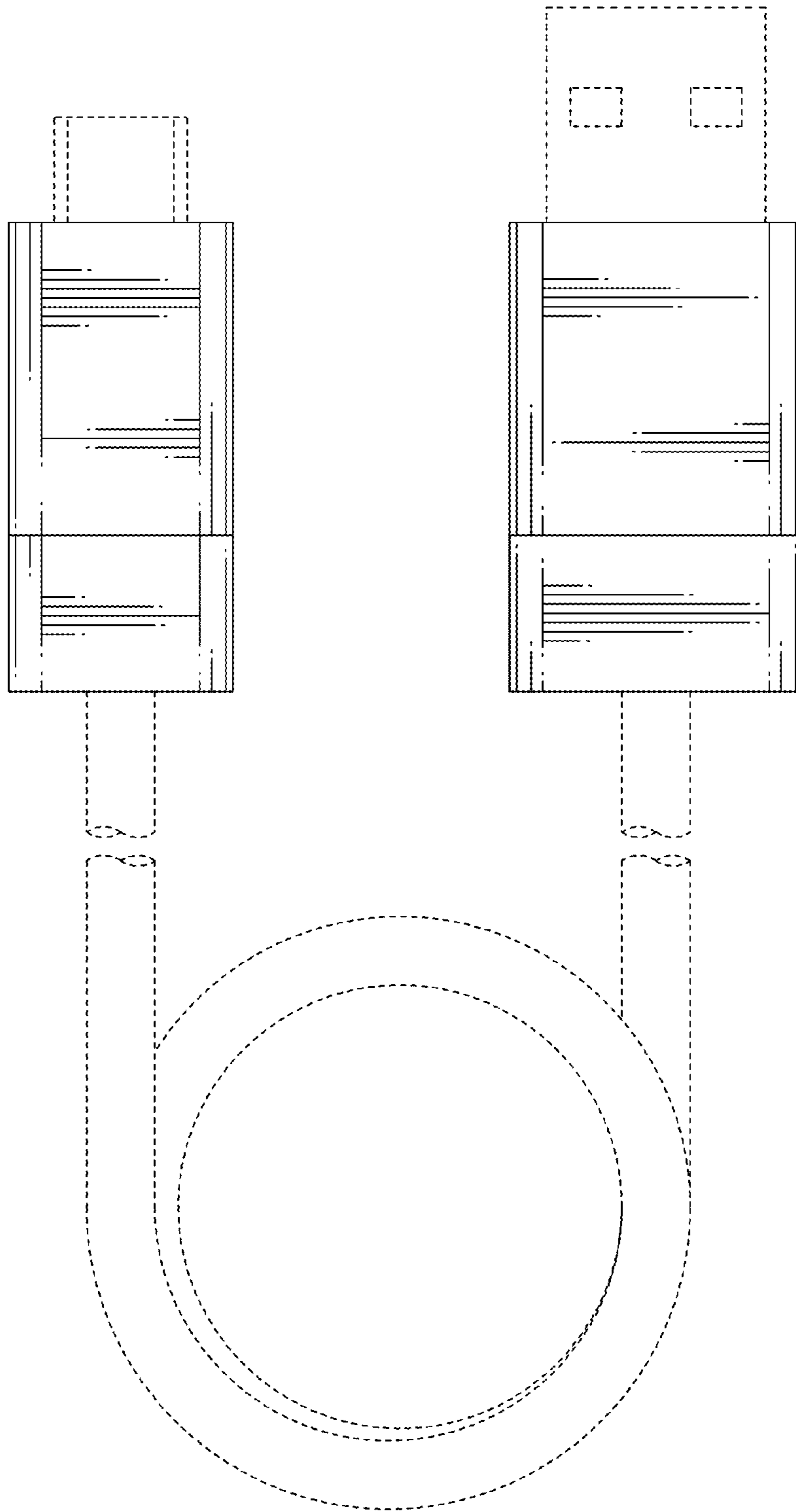


FIG. 3

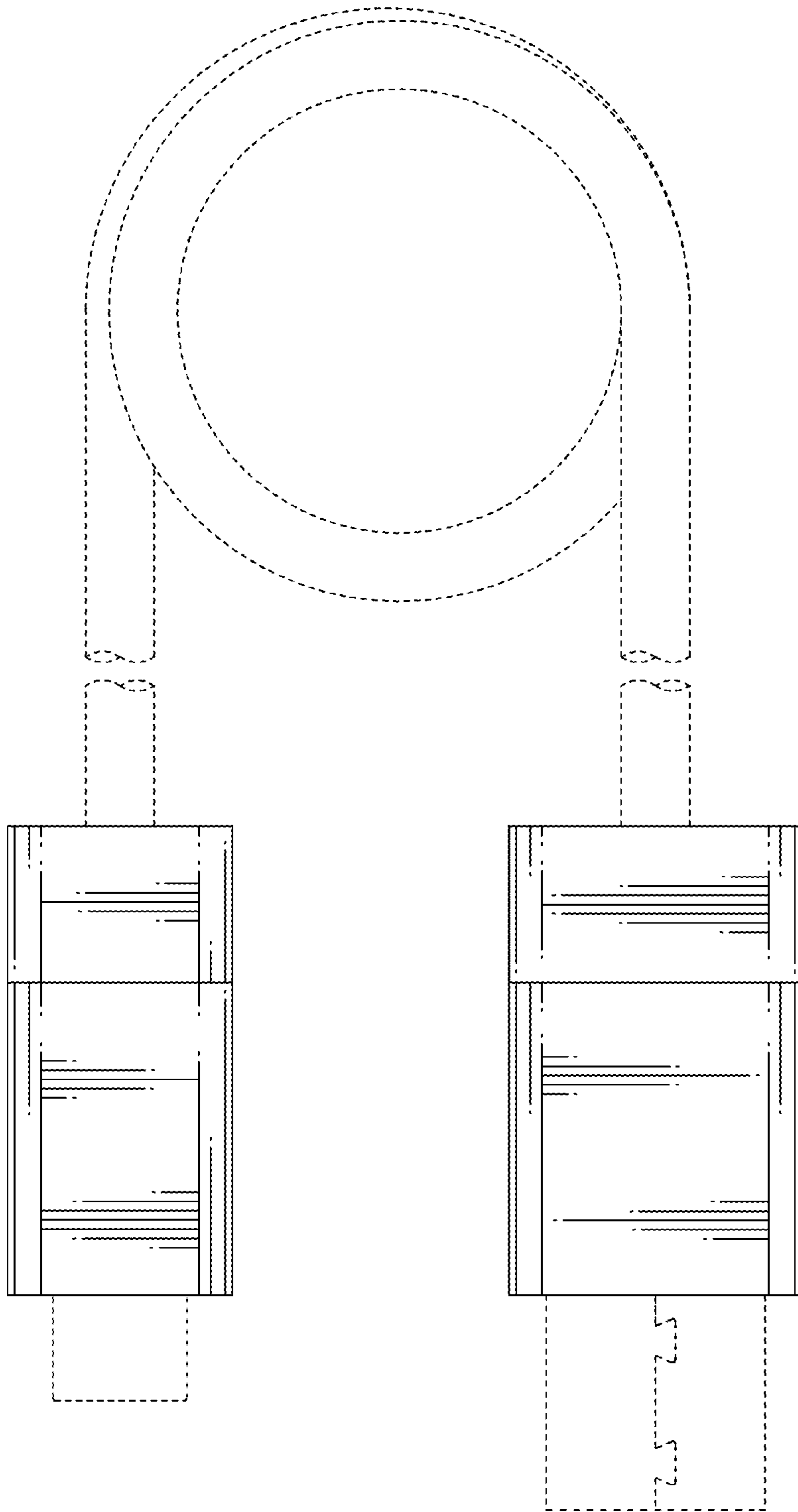


FIG. 4

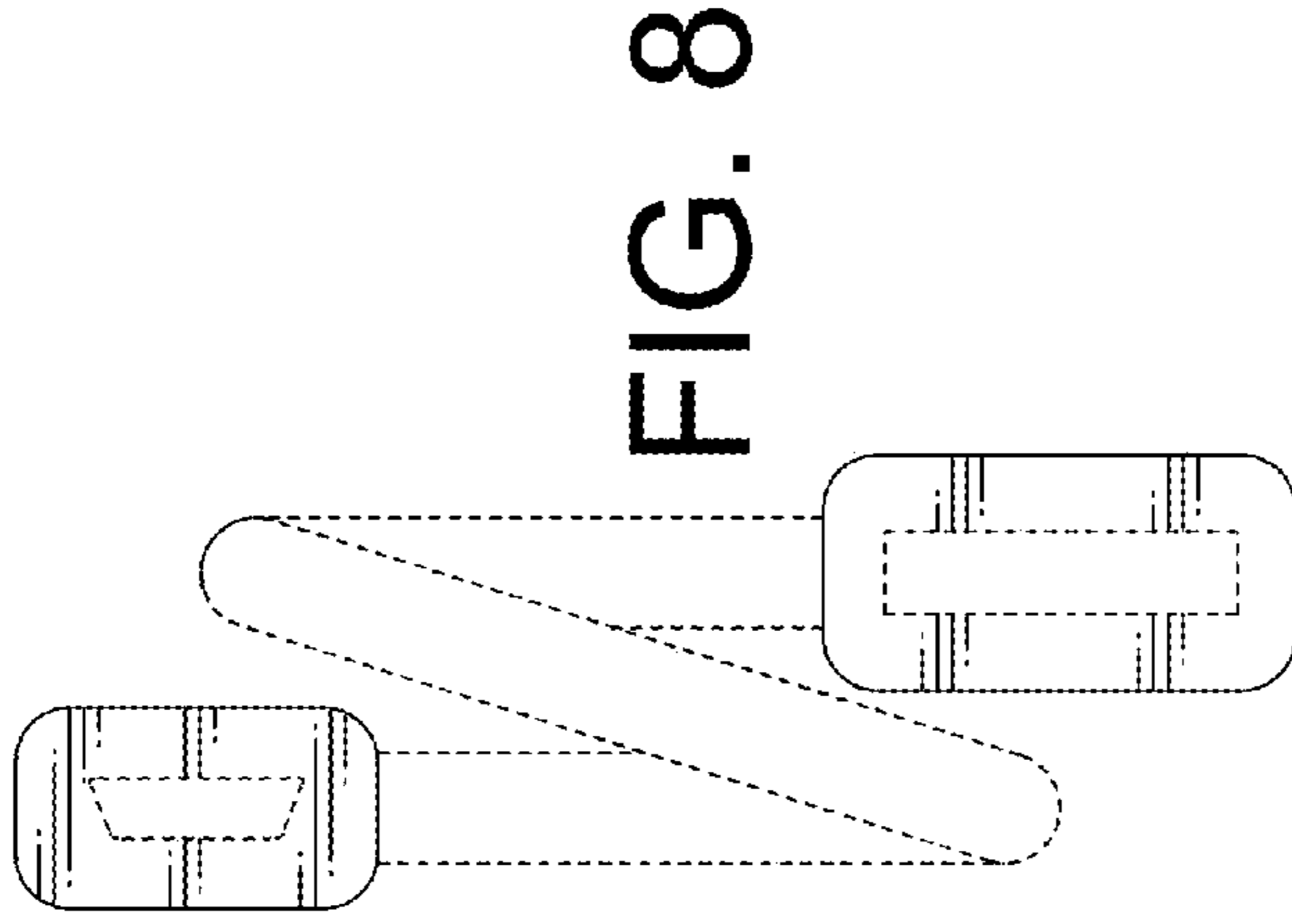


FIG. 8

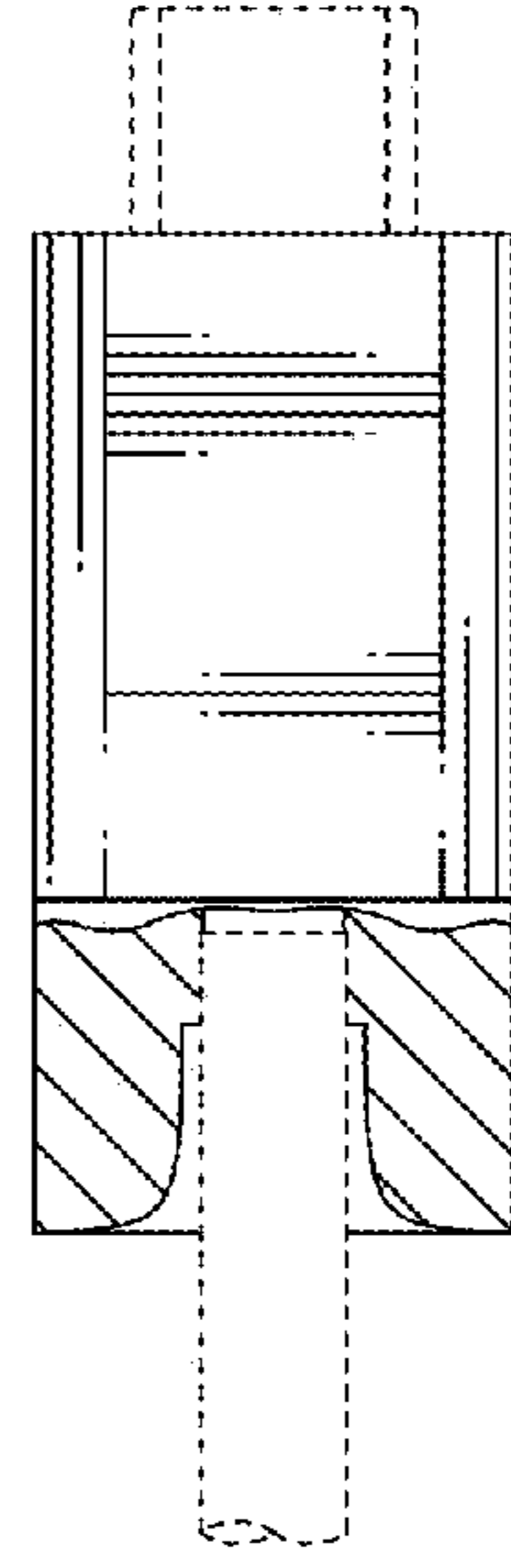


FIG. 7

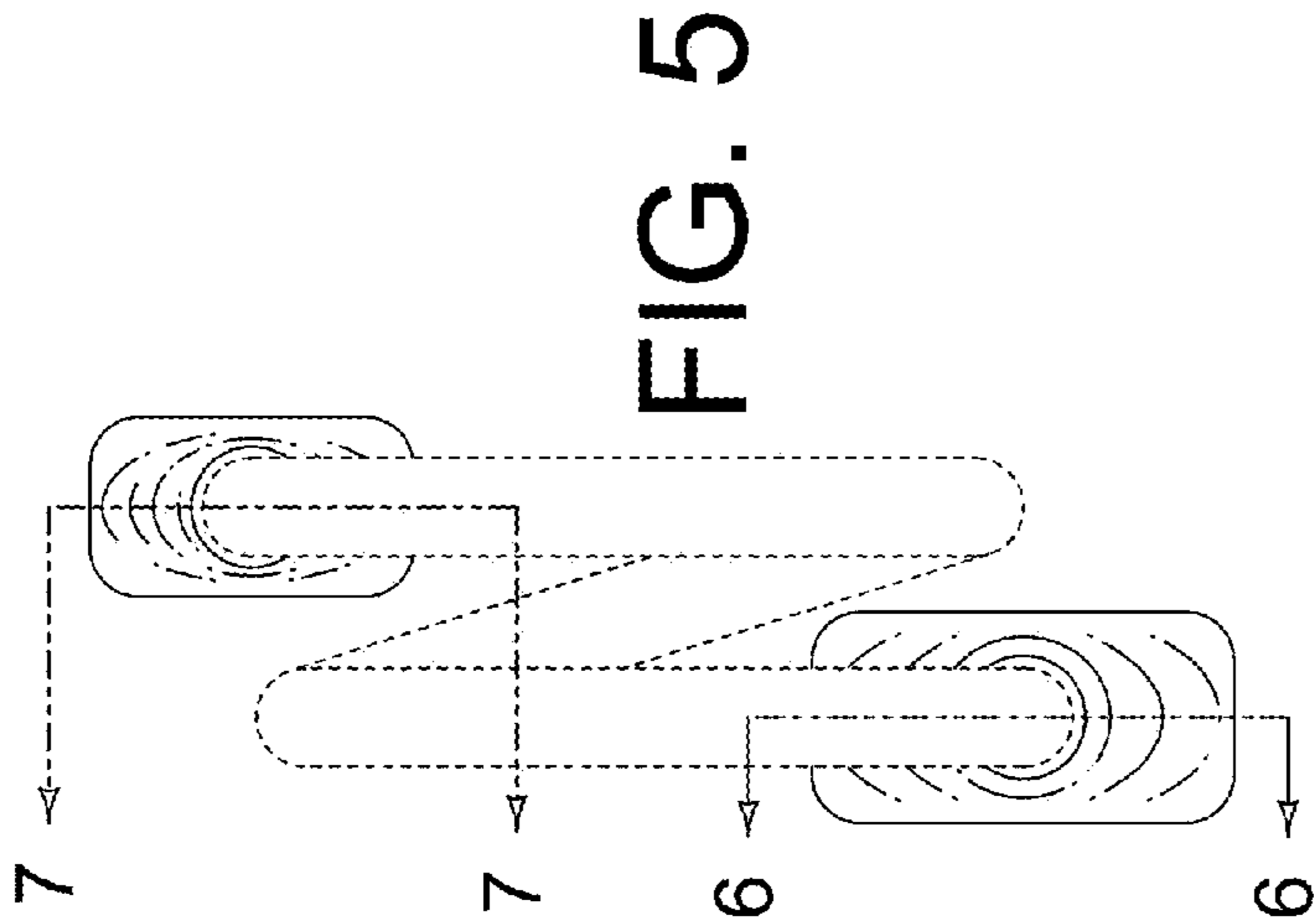


FIG. 5

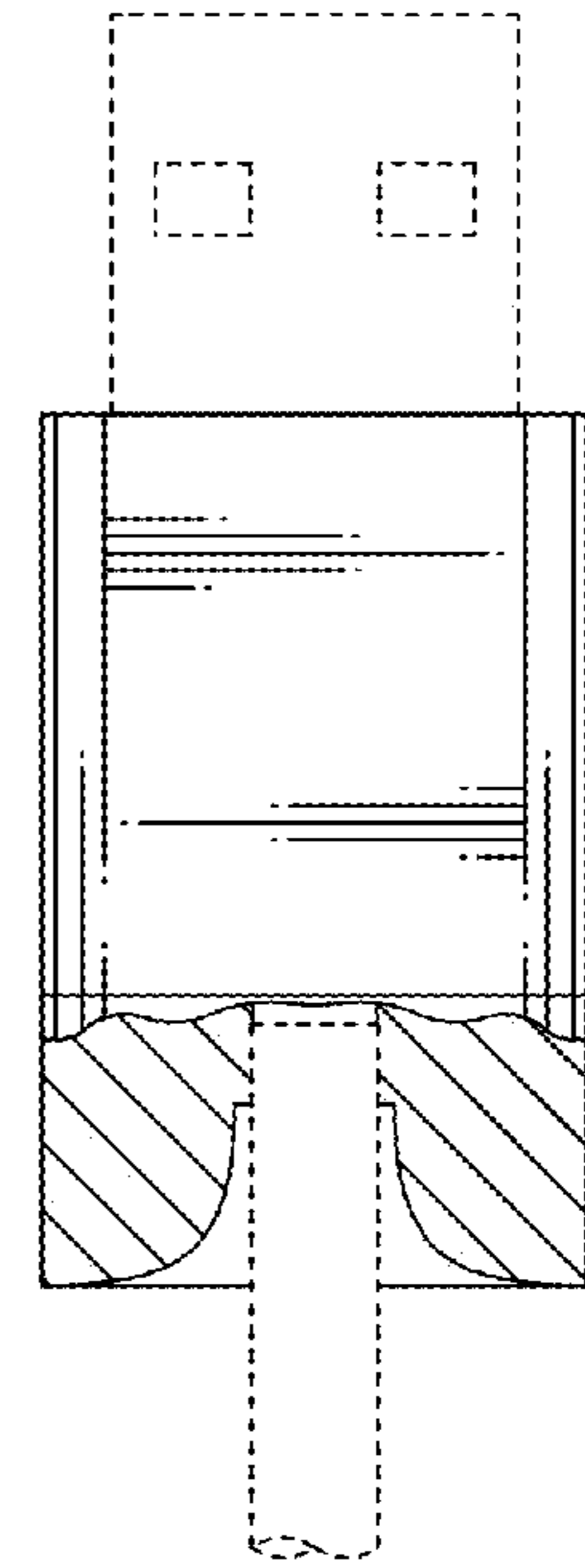


FIG. 6

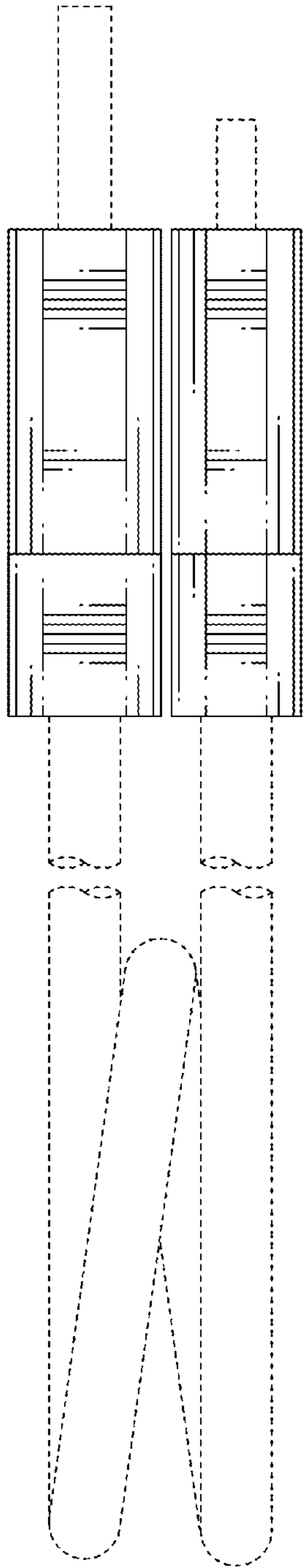


FIG. 9

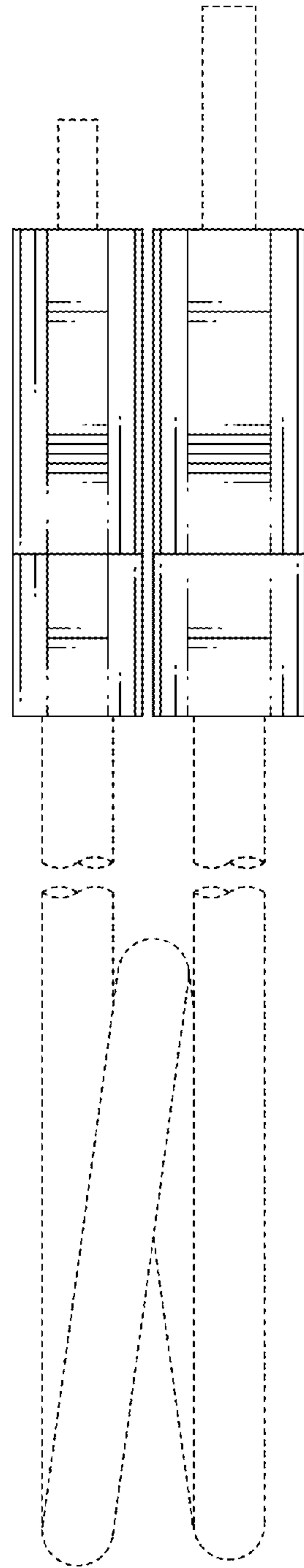


FIG. 10